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# (12) United States Design Patent

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(54) **GROOVES FORMED AROUND A SEMICONDUCTOR DEVICE ON A CIRCUIT BOARD**

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(58) **Field of Classification Search** ..... D13/182; 174/250, 251, 253, 254, 255, 256, 265, 260, 174/261; 361/760, 748, 720; 336/200
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for grooves formed around a semiconductor device on a circuit board, as shown and described.

**DESCRIPTION**

FIG. **1** shows a plan view of the grooves formed around a semiconductor device on a circuit board showing the design according to the invention.

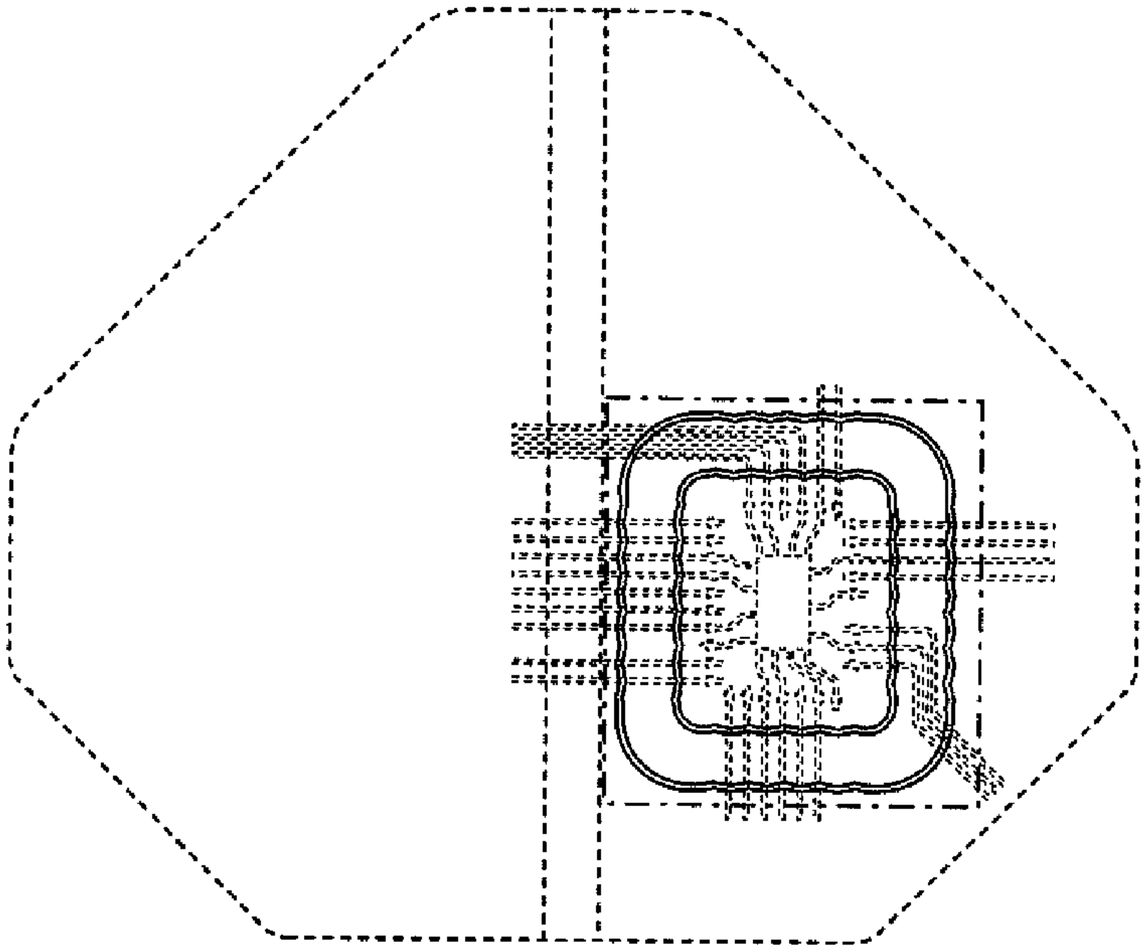
FIG. **2** shows an enlarged view of a claimed portion as identified by the area boxed by the dash-dot-dash line in FIG. **1**.

FIG. **3** shows an enlarged sectional view along the line **3**—**3** in FIG. **2**; and,

FIG. **4** shows an enlarged sectional view along the line **4**—**4** in FIG. **2**.

The elements shown in broken lines and dash-dot-dash lines are for illustrative purposes only and form no part of the claimed invention.

**1 Claim, 2 Drawing Sheets**



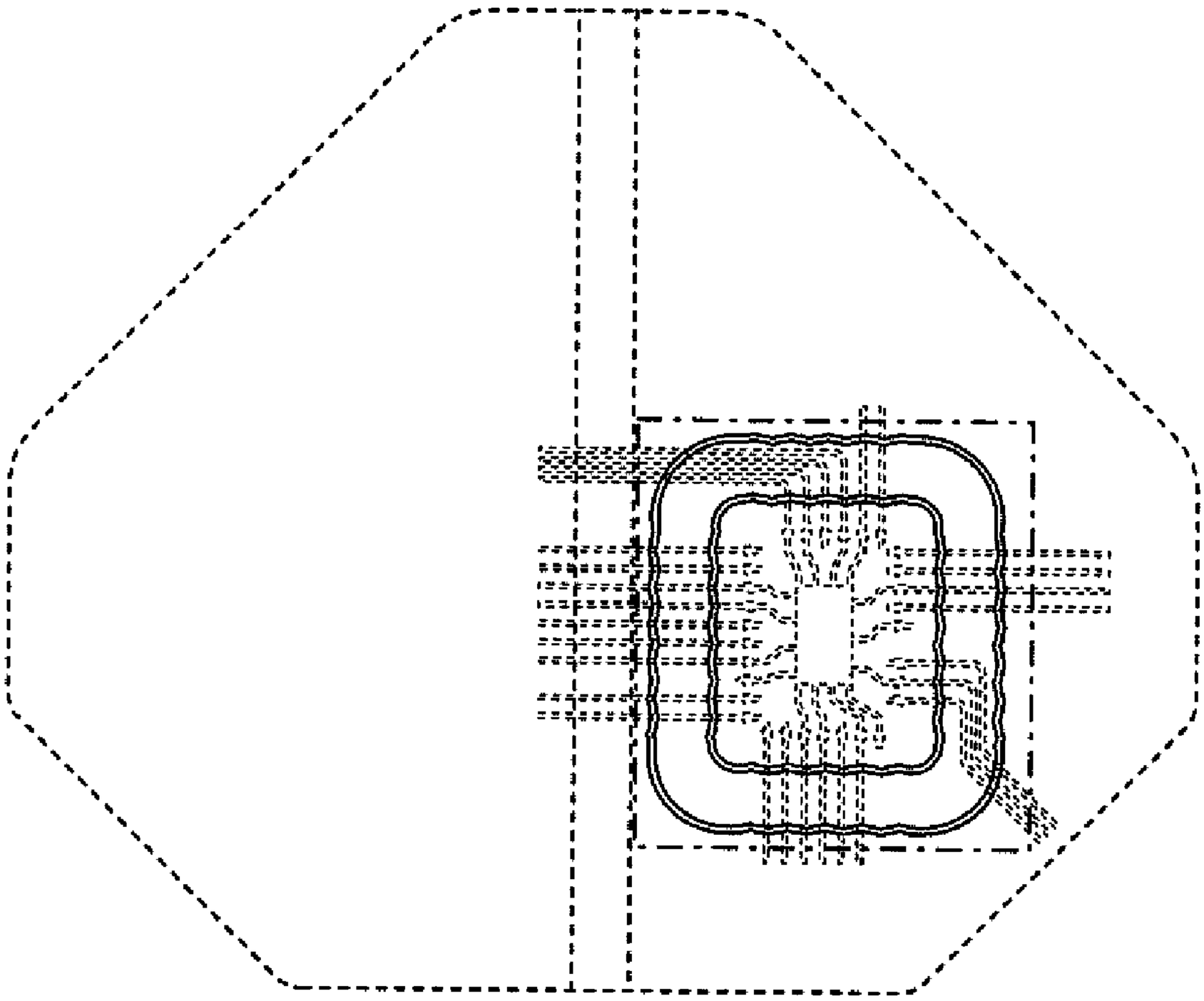


*FIG. 1*

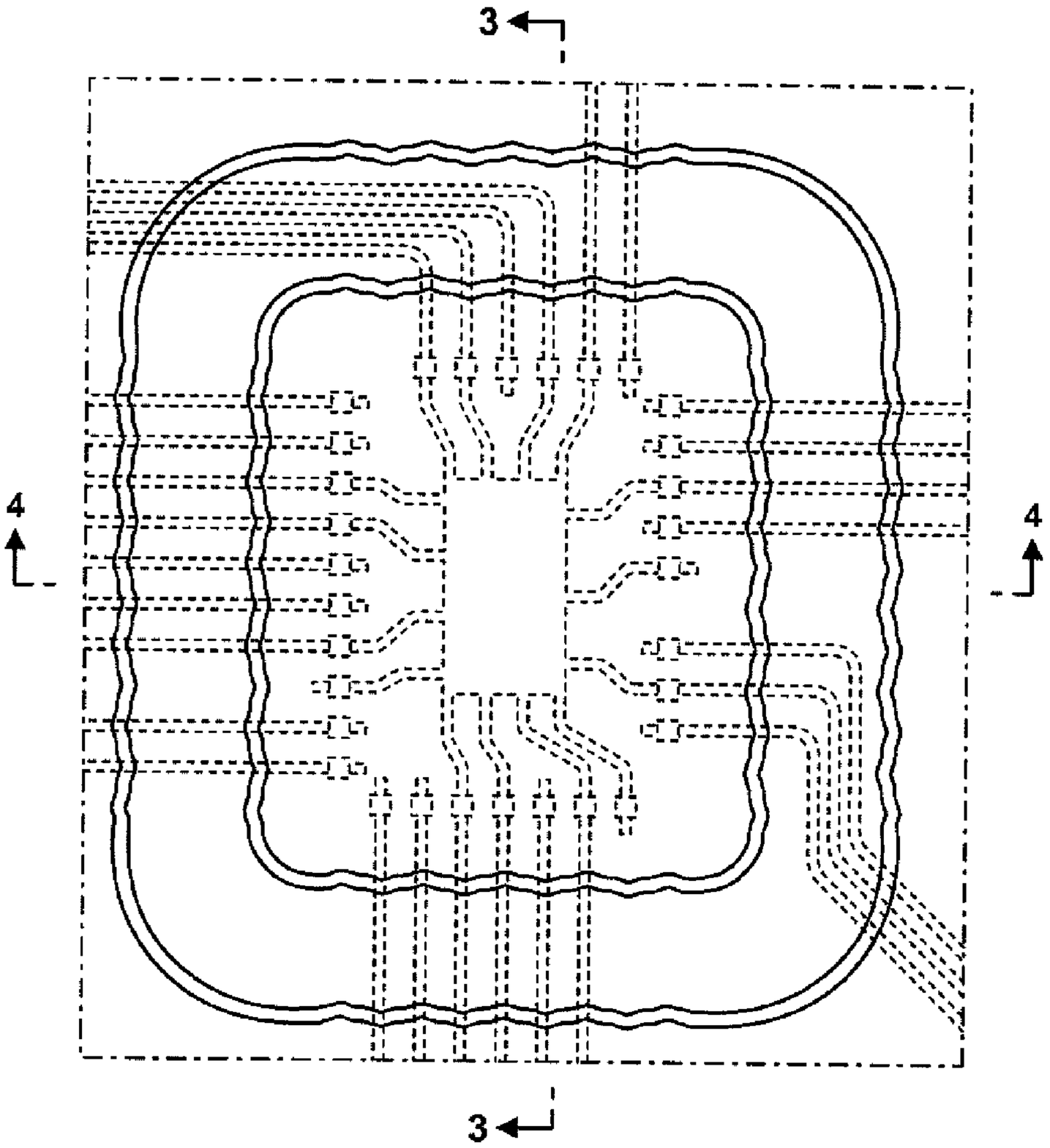



FIG. 2

FIG. 3

FIG. 4